

Title (en)

Selective plating method

Title (de)

Verbessertes selektives Plattierungsverfahren

Title (fr)

Procédé de placage sélectif

Publication

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Application

EP 99202857 A 19990902

Priority

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Abstract (en)

The invention relates to a process for providing objects with a metal plating. More specifically it relates to electrolytically plating of objects, which objects comprise areas that should be plated and areas that should not be plated. It has been found that the ratio between the thickness of the plating layer on the areas that should not be plated, and the areas that should be plated can be lowered by first plating both areas and then removing parts of the plated layers by stripping.

IPC 1-7

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IPC 8 full level

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CPC (source: EP)

C25D 5/022 (2013.01); **C25D 7/04** (2013.01); **C25F 5/00** (2013.01)

Citation (search report)

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